

Agenda - Part I (start 14:00)

1. Last meeting's action points
2. Progress and issues to be raised per partner
 - a. TU/e
 - b. Smart Photonics
 - c. Bright Photonics
 - d. Effect Photonics
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3. Summary

Chips WP3

MPW parallel chips **MPW commercial chips** (x) = reserve space for design

		SP19	SP20	SP21	SP22	SP23	SP24	SP25	SP26	SP27	SP28	SP29	SP30
		Dec-16	Mar-17	Jun-17	Sep-17	Dec-17	Mar-18	Jun-18	Sep-18	Dec-18	Mar-19	Jun-19	Sep-19
			1st					2nd			3rd		
Modulator	Plating chip + parameter extraction	x		x		x		x					
	Modulator chip (Effect+SI+plating)			x	x	x	x	→WP2					
	Al-MQW parallel wafer							x	x	x	x	→WP2	
	CL-TWE chip										x	x	x
RF Line	Conventional design				x	x	x			x	x	x	
	2 nd level metal RF line				x	x	x	x	x				
BB test cell	Wafer level test		x	x	x	x	x	x	x	x	x	x	x
	Die level test		x	x	x	x	x	x	x	x	x	x	x
	Composite BBs				x								
Prec. Filter	(ring, AWG, MZI)			?			?			?			
Low LW LD													
	DBR laser				x		x		x		x		x
	Triplex Hybrid				X (tbd)								
	High Q cavity laser									?			
Demo	both chips								x				

- Not a standard RF Line BB yet. PDK has the attached one to RF modulator
- Performed tests on different geometries
- Systematic tests needed
- Simulation optimum has been found

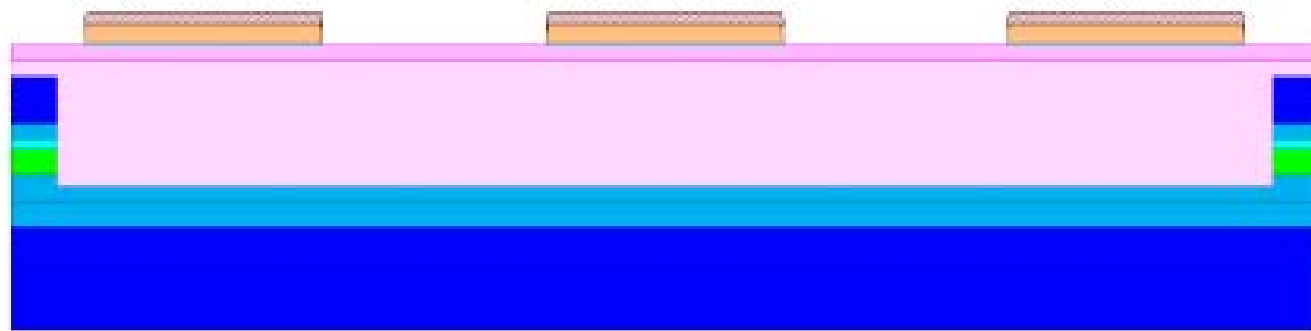
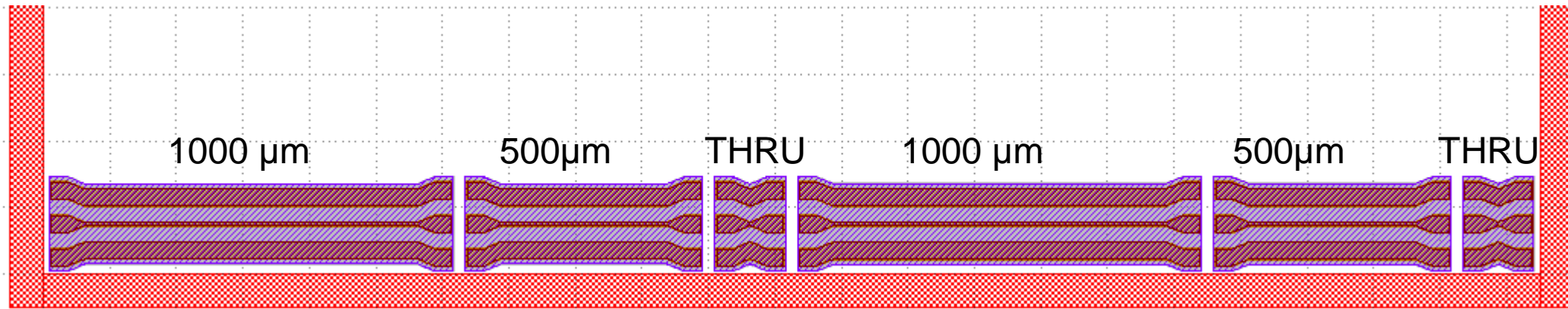
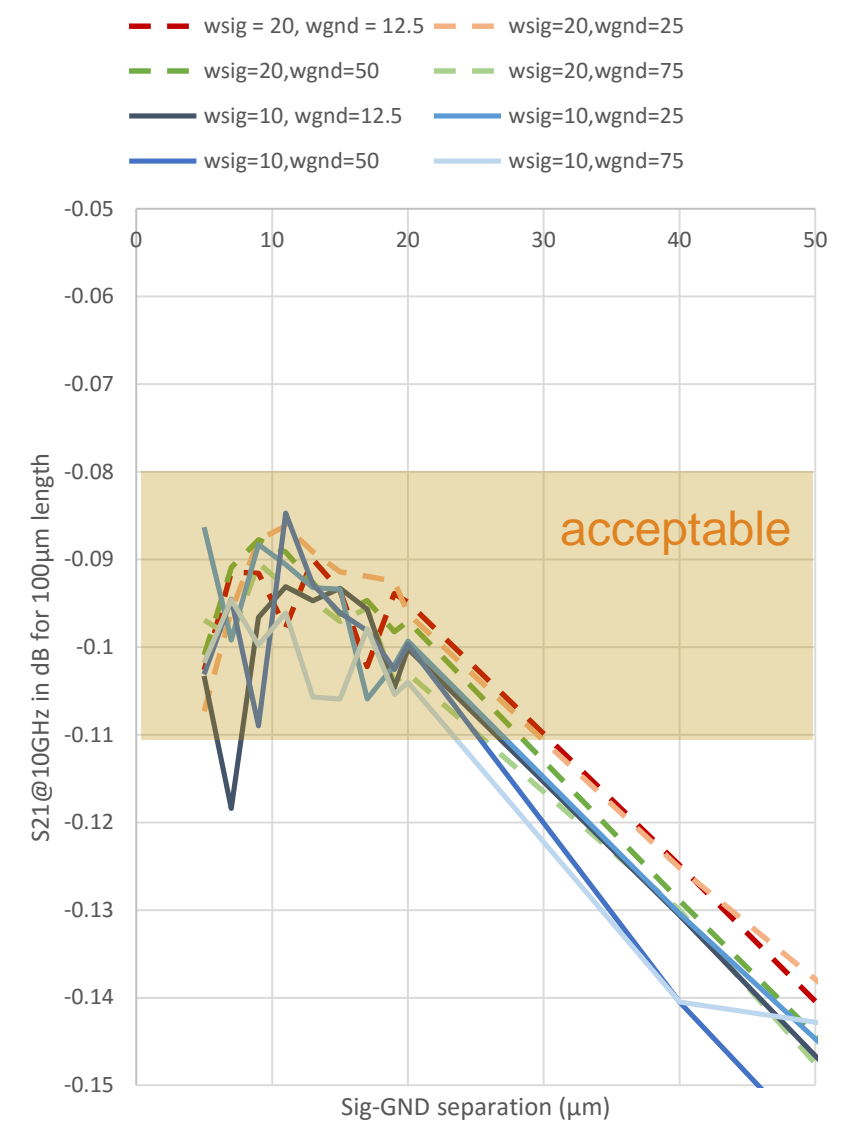
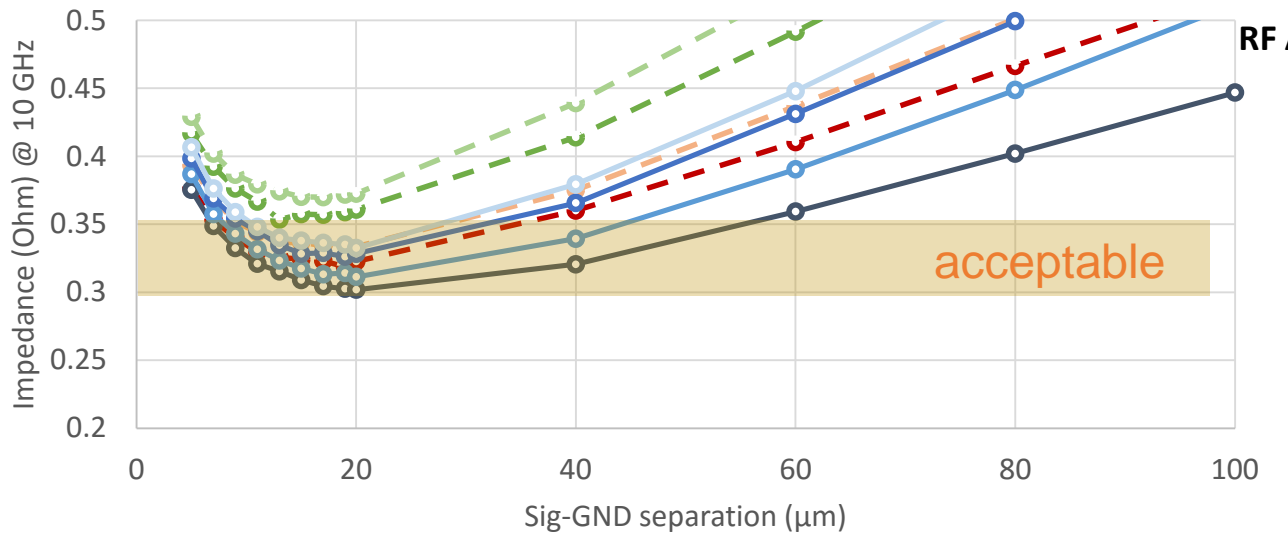
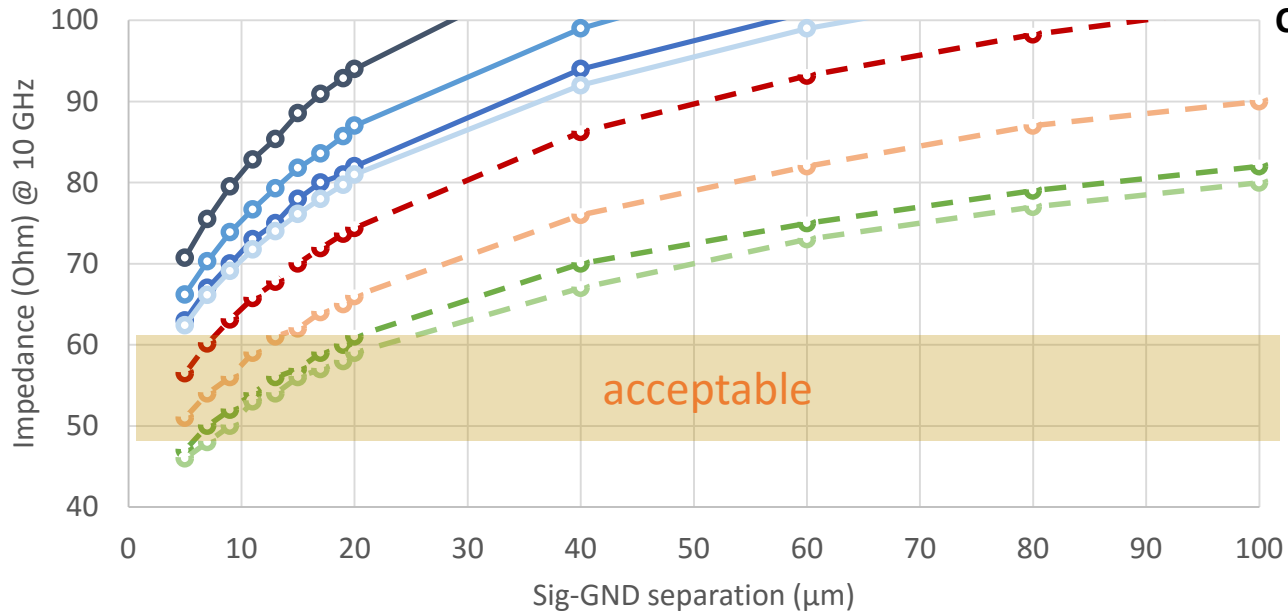
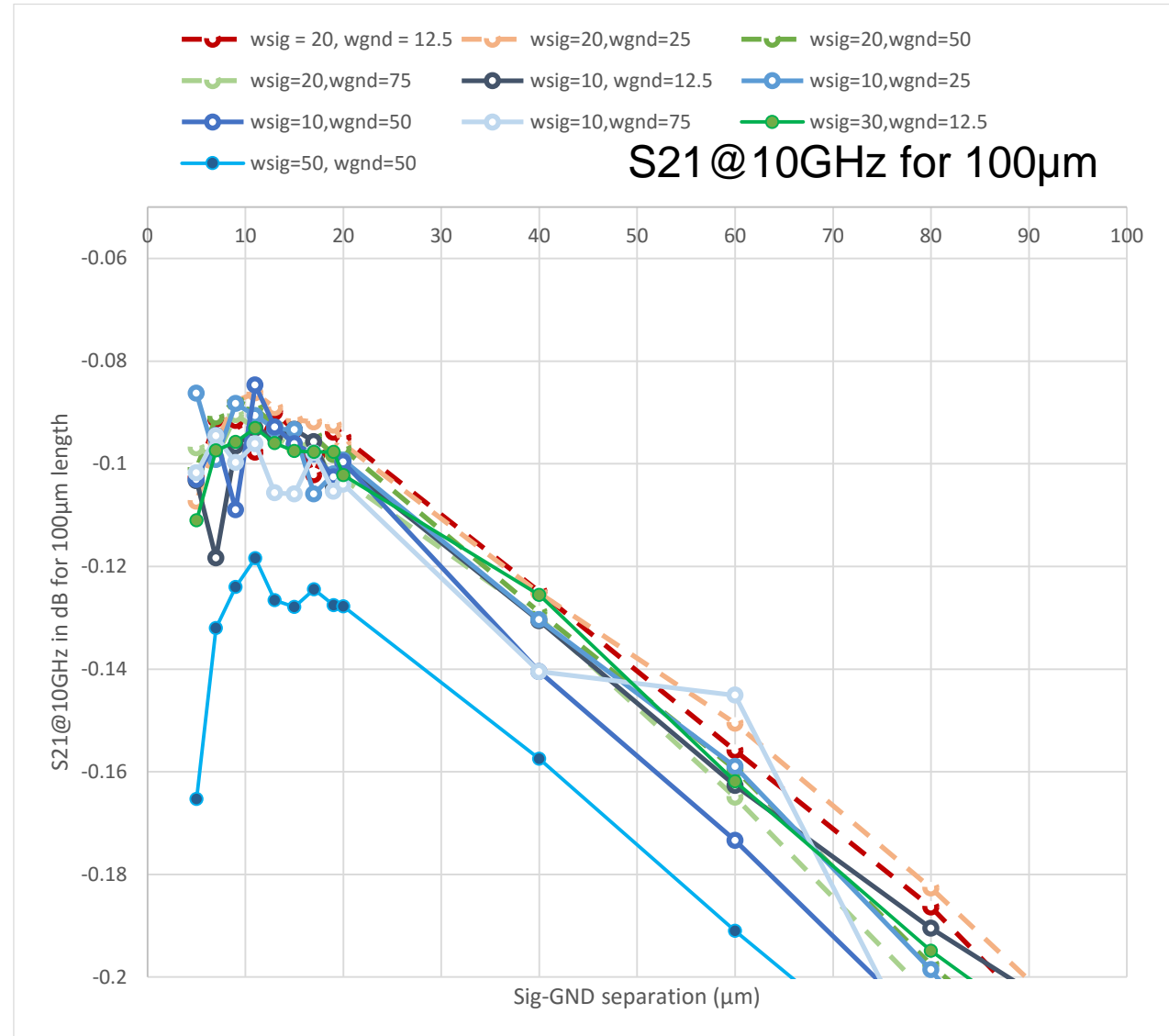
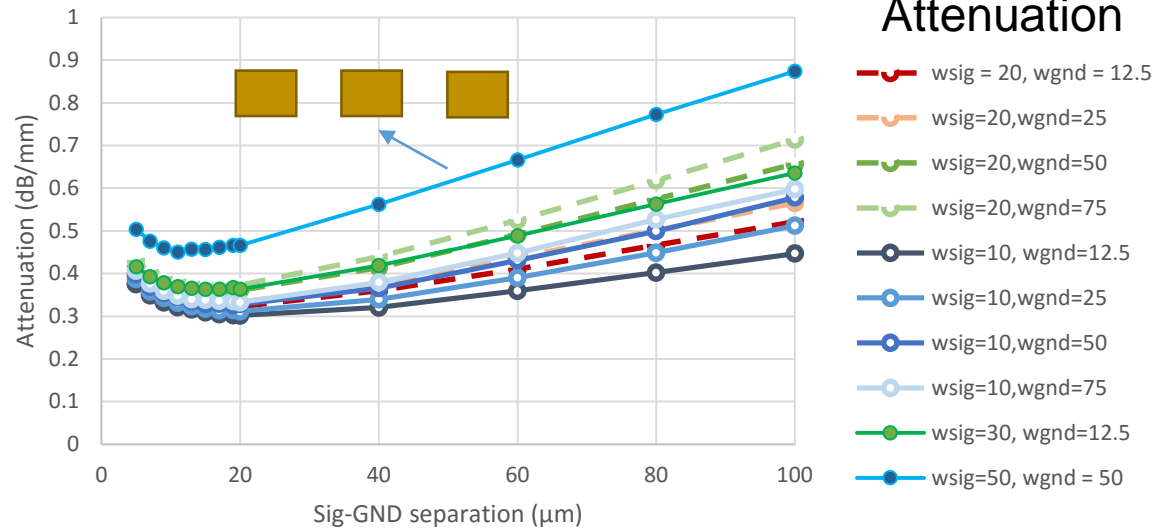
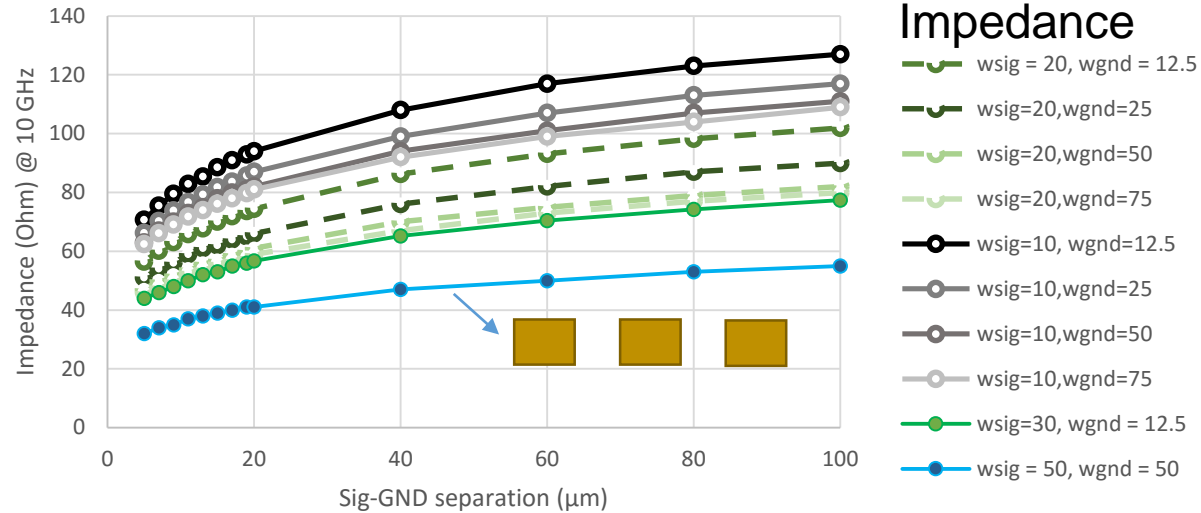


Figure 12.1: Cross-section of a GSG CPW pad.

Parameters



Extended RF line range (going to pad sizes)

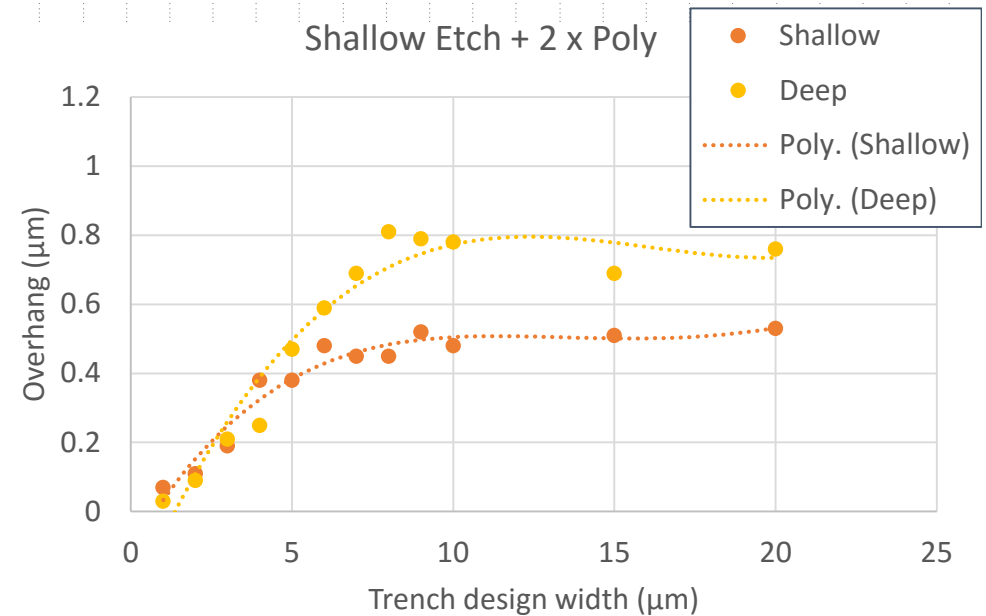
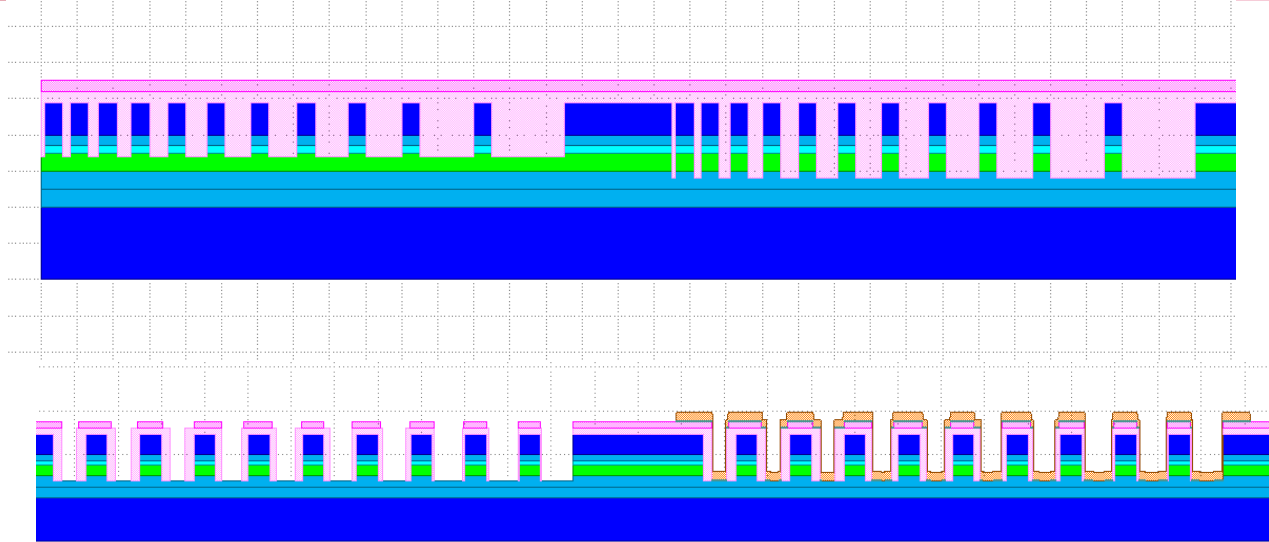
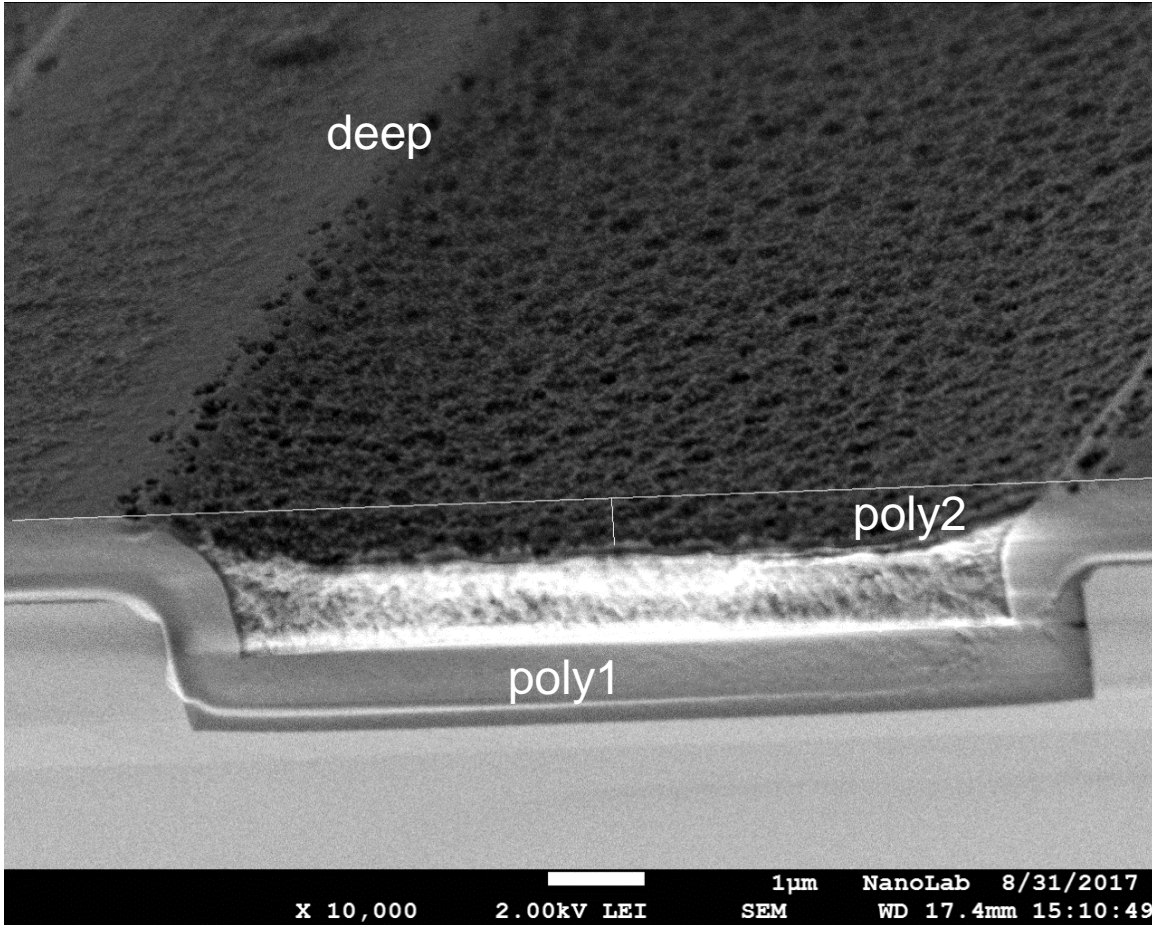


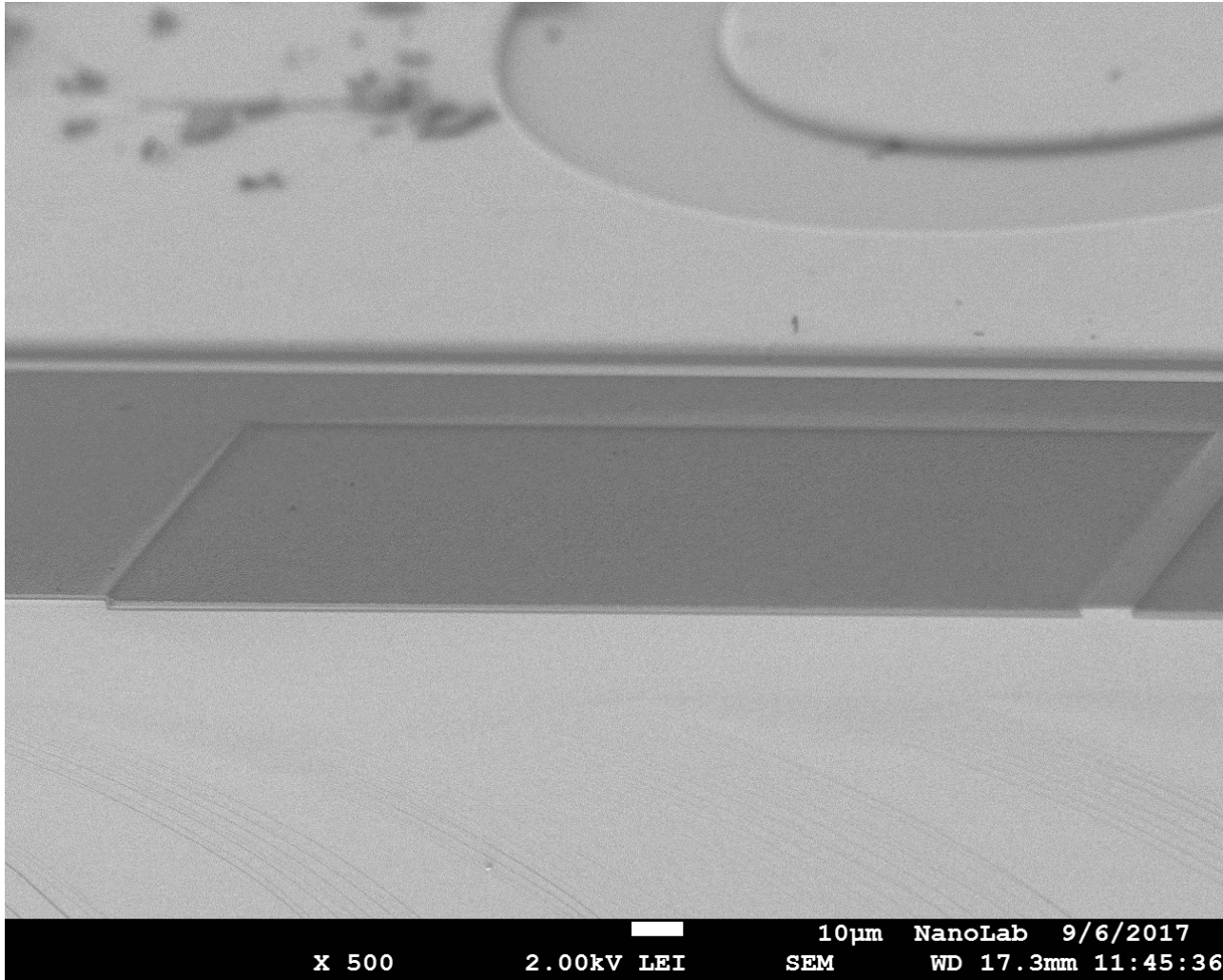
- 20 μm signal width seems more appropriate
- Sig-gnd separation $<20 \mu\text{m}$ but also $>8 \mu\text{m}$ to reduce attenuation
- 20-10-25 seems to be a good candidate

- DOE range
- Sig-gnd 5-20

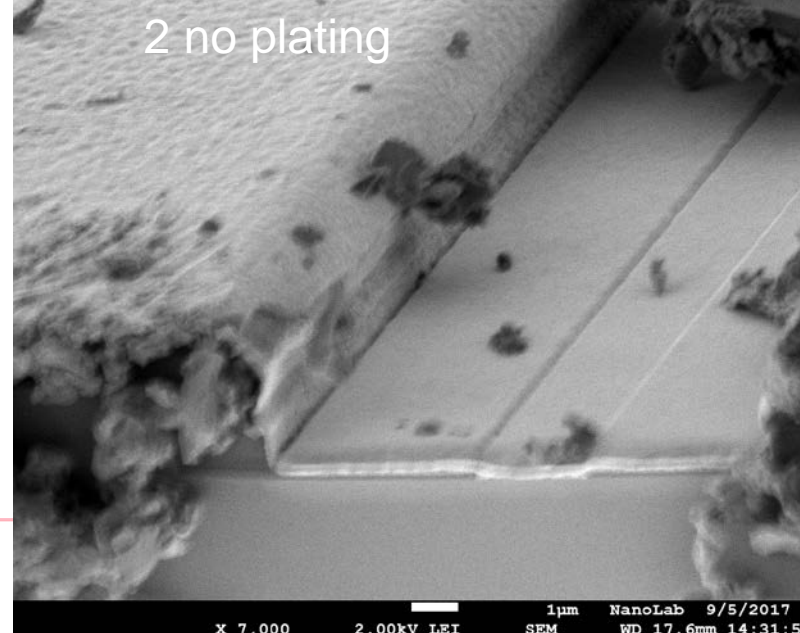
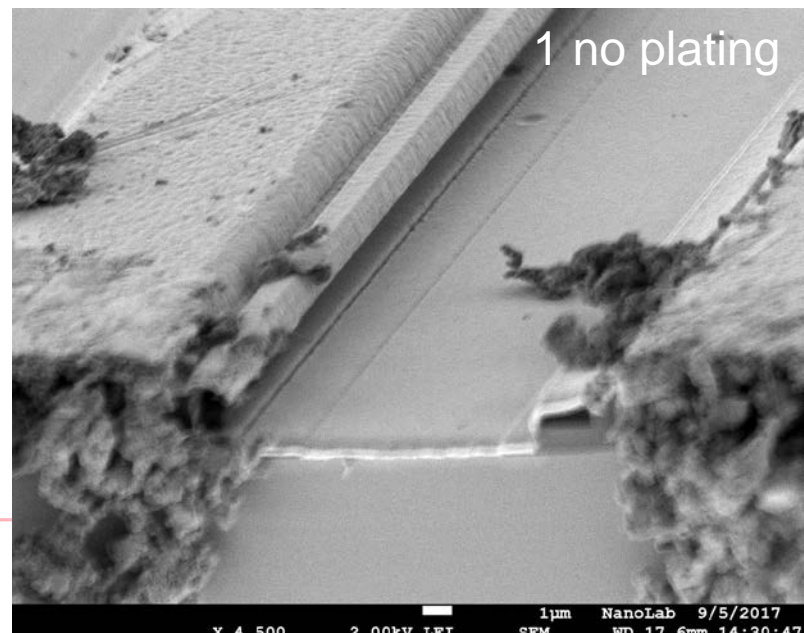
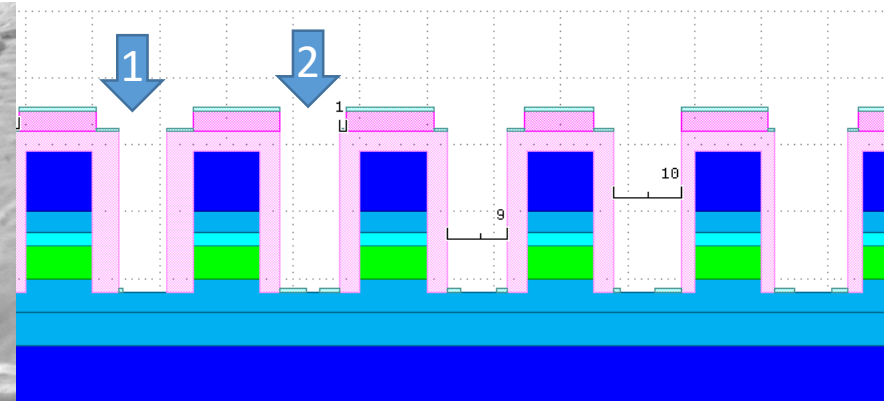
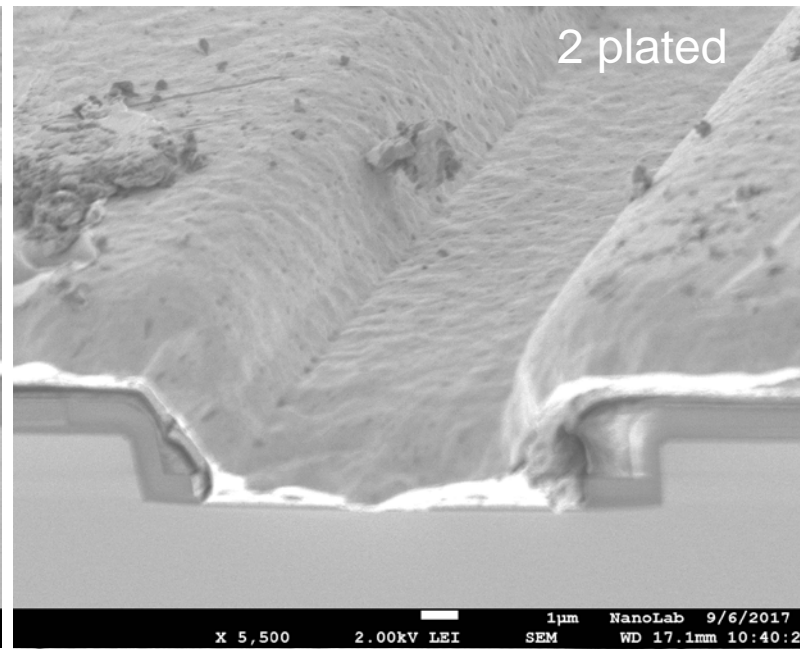
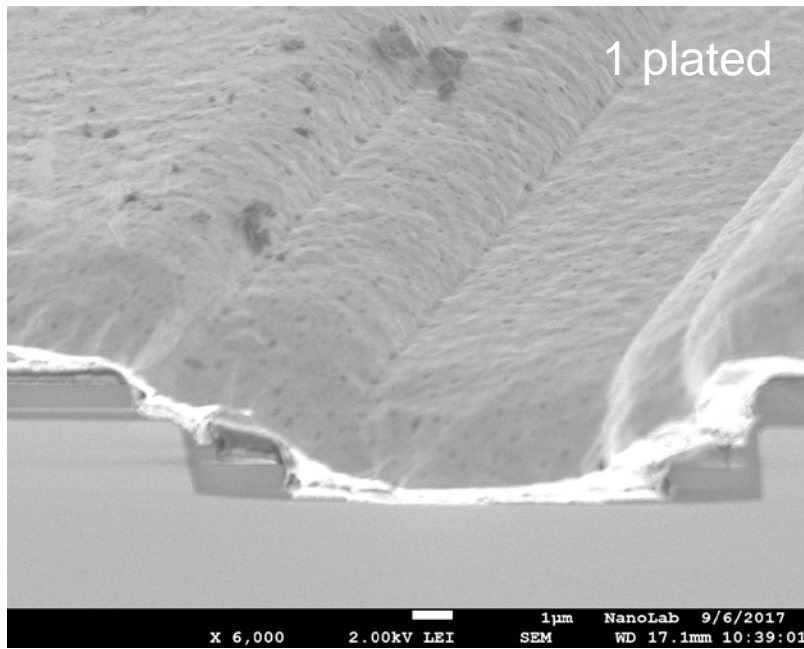
- EAM
- MZM
- Widely tunable laser
- DBR laser
- CC laser

SP19 Results





SP 19 Results



Electrical Measurements !

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